



**PACKAGING ADHESIVE/SEALANT
FORMULATION RJ-9F**

Formula RJ-9F is a specifically designed b-staged epoxy for attaching ceramic, metal, or plastic lids to packages having a mismatch in thermal expansion coefficients. It is especially advantageous for attaching aluminum or plastic lids to ceramic or PC board packages.

TYPICAL PROPERTIES

Max operating temperature (continuous), °C	160-165°C
Outgassing	0.7%TML, 0.04%CVCM
Moisture absorption (24 hr. soak in water @ 100°C)	0.2%
Total ionic content (specific electrical conductance), mS/m	NA
Extractable Ions, ppm	<10
Hydrolysable chloride content, ppm (MIL-STD 883H Method 5011.5)	NA
Ultimate Tg by DSC, °C	102
Modulus, psi	250,000
CTE, ppm/°C	32
Dielectric constant (@ 1MHz)	3.6
Volume resistivity, Ohm-cm	3×10^{16}
Thermal conductivity, W/m-k	0.3 – 0.5

TYPICAL SEALED PACKAGE PERFORMANCE PROPERTIES

Reflow temperature, °C	NA
Lap shear strength (gold/ceramic @ 25°C), psi	6200

**These values may vary depending upon the materials to which the epoxy is adhered. All above data is based on sealed packages consisting of a ceramic header and a ceramic lid.*

SEALING AND CURING

Most parts can be sealed and cured in a one-step cycle of 60 minutes at 160 °C under 5 psi of pressure. For alternate curing practices or automatic sealing procedures, please consult RJR Technologies Customer Service. (Phone 510-638-5901 or Fax 510-638-5958)

STORAGE AND HANDLING

Keep parts with the material in vacuum sealed bag with dry-packs at 3-8°C and <50% RH. Shelf life of the material when stored under refrigerated conditions (3-8°C) is 6 months from the date of manufacture. Room temperature and frozen storage conditions may be appropriate for some applications. Please consult RJR Technologies Customer Service for specific storage options.

REGULATORY

This product is RoHS compliant.

NOTICE

This data is provided for guideline purposes. No warranty is made on the actual use. Customers should perform their own tests and qualifications.